g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-DS200TBQBG1A**

Test Procedure for a DS200TBQBG1 terminal board

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	G. Chandler	7/1/2010
B	Added step 6.2 on burning in card	G. Chandler	12/12/2013
C			

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G. Chandler			Charlie Wade
DATE	**DATE**	**DATE**	**DATE**
7/1/2010			7/1/2010

1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		30VDC Power or higher

6. TESTING PROCESS

6.1 Testing Procedure

6.1.1 Apply +25Vdc to the + side of capacitor C1 and connect com. to the – side of capacitor C1.

6.1.2 Verify +24Vdc +/- 5% at the following terminal pins on the TB connector.

Terminal Connector
1
5
9
15
19
23
27
31
35
39
43

6.1.3 Use LOU-GE-COMPTEST to test the remainder of the card.

6.2 Burning in card

6.2.1 Connect +27vdc to JHR-3 with common to JHR-4.

6.2.2 Connect a 470 ohm, 2w resistor from common to the following points.

6.2.3 TB1-1, TB1-5, TB1-9, TB1-15, TB1-19, TB1-23, TB1-27, TB1-31, TB1-35, TB1-39 and TB1-43.

6.2.4 Verify +24vdc +/- 1vdc at each of the TB1 connections

6.2.5 Normal repairs; Burn card in for 1 hours and verify +24vdc +/- 1vdc at each of the TB1 connections.

6.2.6 **All Revitalization Cards shall be burned-in for three (3) hours, check text box in SAP to determine if they fall into this category.**

6.3 ***TEST COMPLETE ***

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.